

bq51010BEVM-764 Evaluation Module (WCSP Package)

The bq51010BEVM-764 (EVM) wireless power receiver evaluation kit from TI is a high-performance, easy-to-use development kit for the design of wireless power solutions. The EVM helps designers to evaluate the operation and performance of the bq51010B, 7-V power supply for wireless power transfer. The bq51010B devices provide AC/DC power conversion and regulation while integrating the digital control required to comply with the Qi-communication protocol. The kit speeds up the development of end-use applications.

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1 Considerations with this EVM

The bq51010BEVM-764 evaluation module (HPA764-005) demonstrates the receiver portion of the bqTESLA™ wireless power system. This receiver EVM is a complete receiver-side solution that produces 7-V output at up to a 720-mA load (5 W).

- The bqTESLA receiver is used in any number of low-power battery portable devices such as a power supply to a direct battery charger. With contact-free charging capability, no connections to the device are needed.
- Output voltage of 7 V up to 720-mA charge current
- External adapter switchover
- Low-profile, external pick-up coil
- Frame is configured to provide correct receiver to transmitter spacing
- Room above coil for testing with battery, key for tuning
- Option to adjust the max output current using variable resistor R16

2 Modifications

Refer to the datasheet when changing components ([SLUSBB8](#)). To aid in such customization of the EVM, the board was designed with devices having 0603 or larger footprints. A real implementation likely occupies less total board space.

Note that changing components can improve or degrade EVM performance.

3 Recommended Operation Condition

[Table 1](#) provides a summary of the bq51010BEVM-764 performance specifications. All specifications are given for an ambient temperature of 25°C.

Table 1. bq51010BEVM-764 Electrical Performance Specifications

Parameter		Test Condition	MIN	TYP	MAX	UNIT
V _{IN}	Input voltage range	Typical Vrect Voltage at TP12	4		10	V
V _{adapter}	Adapter input voltage		4	7	20	V
OVP	Input overvoltage protection	Voltage at V-rectified			750	mA
I _{OUT}	Output current range	Current limit programming range			750	mA
V _{OUT}	Output voltage	I _{LOAD} = 700 mA		7		V
F _s	Switching frequency		110		205	kHz
Efficiency	AC-AC efficiency			76		%

4 Equipment and EVM setup

4.1 Schematic

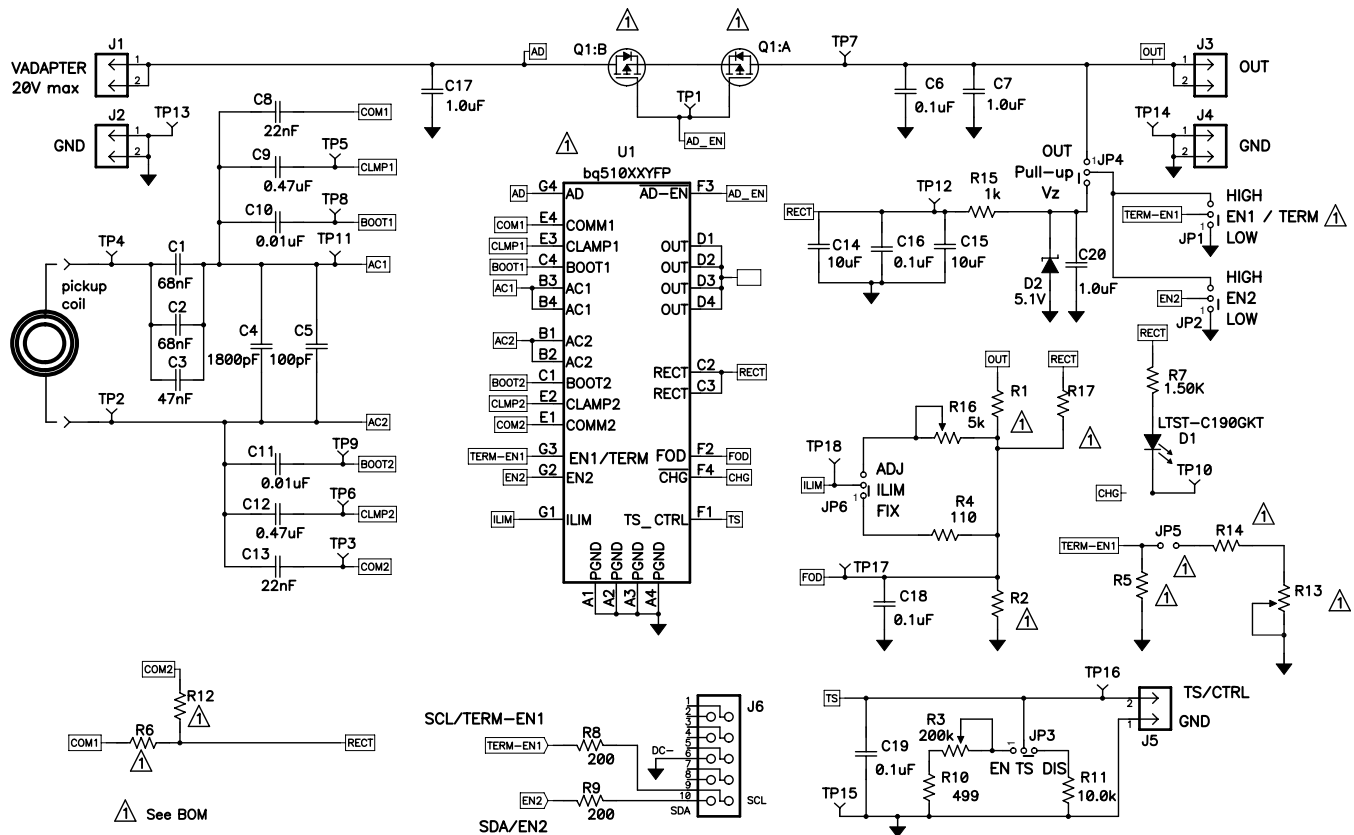


Figure 1. HPA764 Schematic

4.2 Connector and Test Point Descriptions

The connection points are described in the following paragraphs.

4.2.1 J1 – AD External Adapter Input, J2-GND

Power cannot be provided to simulate an external adapter applied to the receiver in this bq51010BEVM-764 (HPA764-005).

4.2.2 J3 – Output Voltage, J4-GND

Output voltage is 7 V in wireless power mode up to 750 mA.

4.2.3 J5 – TS and Return Connector

External connection for temperature sense resistor, see the datasheet for additional information.

4.2.4 J6 – Programming Connector

This connector is populated and is only useful at the factory level for programming the IC.

4.3 Jumpers and Switches

The control jumpers are described in the following paragraphs.

4.3.1 JP1 – EN1 Enable 1

Not populated in this EVM (HPA764-005).

4.3.2 JP2 – EN2 Enable 2

Enable signal input that allows the system to assert wireless charging. If EN2 is set to low, wireless charging is enabled unless AD voltage > 3.6 V. If EN2 is set to High, AD mode disabled, wireless charging always enabled. Used when OTG plus wireless charging is active.

4.3.3 JP3 – TS Enable or Disable

This jumper enables the TS adjustment feature using R3. The disable position sets voltage at the TS pin to a safe value. The default shorting jumper setting is disabled.

4.3.4 JP4 – Pull-Up to Out or Vz

EN2 pull-up can be powered from OUT or RECT. Vz is derived from RECT through a resistor and Zener diode D2.

4.3.5 JP5 – Termination

This jumper along with R14 and R13 are not installed in HPA764-001-003-005.

4.3.6 JP6 – ILIM Fix or ADJ

Max output current is set by ILIM pin. In the FIX position, the current is set to a fixed value. In the ADJ position the current is set by R16.

4.4 Test Point Descriptions

The test points are described in the following paragraphs.

4.4.1 TP1 – AD-EN

This push-pull driver for the external PFET connects the adapter and the output from the bq51010B.

4.4.2 TP2 – AC Input 2

This is the test point for measuring AC voltage applied to the EVM from the receiver coil.

4.4.3 TP3 – COM2 Communication 2 Drive

Communication driver signal, open-drain output connected to communication capacitor.

4.4.4 TP4 – AC Input 1

This is the test point for measuring AC voltage applied to the EVM from the receiver coil.

4.4.5 TP5 – CLMP 1

Overvoltage clamp driver signal, open-drain output is connected to OVP capacitor.

4.4.6 TP6 – CLMP 2

Overvoltage clamp drive signal, open-drain output is connected to OVP capacitor.

4.4.7 TP7 – OUT Output Voltage

This test point is the output voltage.

4.4.8 TP8 – Boot-1 Boot Capacitor

This bootstrap capacitor 1 drive connects to the integrated circuit (IC).

4.4.9 TP9 – Boot-2 Boot Capacitor

This bootstrap capacitor 2 drive connects to the IC.

4.4.10 TP10 – CHG Charge

This output signal indicates that the output current is being delivered to OUT, the open-drain output.

4.4.11 TP11 – AC1 IC input

This is the AC input to the IC from series capacitors.

4.4.12 TP12 – Rectified Voltage

The input AC voltage is rectified into unregulated DC voltage; additional capacitance is used to filter the voltage before the regulator.

4.4.13 TP13, TP14, TP15 – GND

These are the ground test points.

4.4.14 TP16 – TS Temp Sensor

This is the connection point for external thermistor; see the data sheet for additional information.

4.4.15 TP17 – FET Open Detection (FOD)

Input for rectified power measurement, pin F2 of the IC.

4.4.16 TP18– ILIM

Programming pin for over current limit, pin G1 of the IC.

4.5 Pin Description of the IC

Table 2. Pin Description

PIN Number (WCSP)	bq51010B
A1, A2, A3, A4	PGND
B1, B2	AC2, AC2
B3, B4	AC1, AC1
C1	BOOT2
C2, C3	RECT
C4	BOOT1
D1, D2, D3, D4	OUT
E1	COM2
E2	CLMP2
E3	CLMP1
E4	COM1
F1	TS/CTRL
F2	FOD
F3	AD-EN
F4	CHG

Table 2. Pin Description (continued)

PIN Number (WCSP)	bq51010B
G1	ILIM
G2	EN2
G3	EN1
G4	AD

5 Test Procedure

This procedure describes test configuration of the bq51010B evaluation board (HPA764-005) for bench evaluation.

5.1 Definition

The following naming conventions are used:

VXXX : External voltage supply name (VADP, VBT, VSBT)

LOADW: External load name (LOADR, LOADI)

V(TPyy): Voltage at internal test point TPyy. For example, V(TP02) means the voltage at TP02.

V(Jxx): Voltage at header Jxx

V(TP(XXX)): Voltage at test point XXX. For example, V(ACDET) means the voltage at the test point which is marked as ACDET.

V(XXX, YYY): Voltage across point XXX and YYY.

I(JXX(YYY)): Current going out from the YYY terminal of header XX.

Jxx(BBB): Terminal or pin BBB of header xx.

JPx ON: Internal jumper Jxx terminals are shorted.

JPx OFF : Internal jumper Jxx terminals are open.

JPx (-YY-) ON: Internal jumper Jxx adjacent terminals marked as YY are shorted.

Assembly drawings have location for jumpers, test points, and individual components.

5.2 Recommended Test Equipment

The following equipment is needed to complete this test procedure.

5.2.1 Power Supplies

A power supply capable of supplying 19 V at 1 A is required for testing procedures.

5.2.2 Loads

A resistive load or electronic load set to 9.5 Ω at 750 mA, 14 Ω at 500 mA, and 5 k Ω at 1 mA, power rating should be 5 W.

5.2.3 Meters

Two DC voltmeters and two DC ammeters are required.

5.2.4 bqTesla Transmitter

The transmitter HPA689 or equivalent is used for final test.

5.3 Equipment Setup

5.3.1 Test Set Up

The final assembly is tested using a bqTesla transmitter provided (HPA689). Input voltage to the transmitter is set to 19 V_{DC}, ±200 mV with current limit of 1 A and connected to J1 and J2. Set power supply to OFF. Place UUT on the transmitter coil. The unit under test (UUT) is placed in the center of HPA689 TX coil.

Other bqTesla transmitter base units are also acceptable for this test.

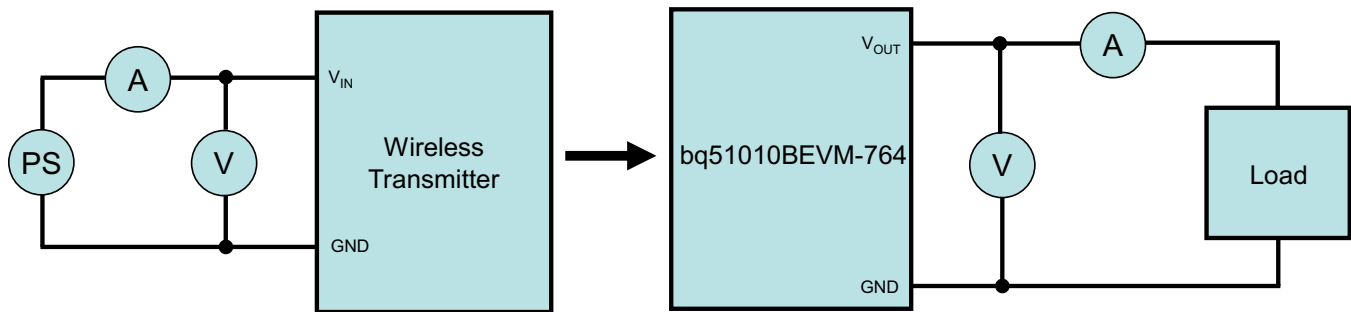


Figure 2. Test Set Up

5.3.2 Load

The load is connected between J3 OUT and J4 GND of the UUT. A DC ammeter is connected between UUT and Load. Set the load for 10 Ω/700 mA.

5.3.3 Jumper Settings

JP1: EN1/TERM and Low shorted

JP2: EN2 and Low shorted

JP3: TS and DIS shorted

JP4: Pullup and Vz shorted

JP5: Open

JP6: ILIM and ADJ shorted

5.3.4 Meters

- Connect ammeter to measure 19-V input current to transmitter.
- Connect voltmeter to monitor input voltage at J1 and J2 of TX unit.
- On UUT, a voltmeter is used to measure output voltage at TP7 with ground at J4.
- Connect ammeter to measure load current.

5.3.5 R3 Set Up

Connect ohmmeter across J5. Connect shorting jumper JP3 from TS to EN. Adjust R3 for a 10 kΩ, ±200-Ω reading on the ohmmeter

5.3.6 R16 Set Up

Connect ohm meter between JP6 ADJ and J2 (GND). Adjust R16 to 415 Ω, ±20-Ω reading on the ohmmeter.

5.4 Procedure

5.4.1 Turn ON Operation and Operation at 500-mA Load

- Turn ON transmitter power supply (19 V)
- Transmitter: Verify LED D2 is *ON*
- UUT: Adjust load current to 700 mA, ± 50 mA
- Put the receiver EVM on the Transmitter coil and align them correctly
- After 5 seconds, verify that:
 1. Transmitter: Status LED D5 should be green flashing for approximately 1 second
 2. The transmitter beeps
 3. Transmitter: LED D2 still *ON*
 4. Receiver: LED D1 is *ON*
- UUT: Verify that V_{out} is 6.9 V to 7.1 V (between TP7 and J4)
- UUT: Verify that the rectified voltage is 7.4 V to 7.05 V (between TP12 and TP13) (**Note:** a modulation signal is present on this voltage every 250 ms and may cause fluctuation in the reading, use lower value or base line)

5.4.2 Efficiency Test (500-mA Load)

- Verify the input current to TX is less than 260 mA, with input voltage at 19 V_{DC}
- Turn OFF Transmitter Power Supply (19)

5.4.3 Operation (1-mA Load)

- Turn ON transmitter power supply (19 V)
- Transmitter: Verify LED D2 is *ON*
- UUT: Adjust load current to 1 mA, ± 200 μ A
- Put the receiver EVM on the transmitter coil and align them correctly
- After 5 seconds verify that:
 1. Transmitter: Status LED D5 is flashing green for approximately 1 second
 2. The transmitter beeps
 3. Transmitter: LED D2 still *ON*
 4. Receiver: LED D1 is *ON*
- UUT: Verify that V_{out} is 6.9 V to 7.1 V (between J3 or TP7 and J4)
- UUT: Verify that rectified voltage should be 10 V to 7.5 V (between TP12 and TP13) (**Note:** a modulation signal is present on this voltage every 250 ms and may cause fluctuation in the reading, use lower value or base line)

5.4.4 Efficiency Test (1-mA Load)

- Verify the input current to TX is less than 80 mA, with the input voltage at 19 V_{DC}
- Turn *OFF* Transmitter Power Supply (19)

5.4.5 Operation (700-mA Load)

- UUT: Adjust load current to 700 mA, ± 50 mA
- UUT: Verify that V_{OUT} is 6.9 V to 7.1 V (between J3 or TP7 and J4)
- UUT: Verify that the rectified voltage should be 7.5 V to 7.05 V (between TP12 and TP13) (**Note:** a modulation signal is present on this voltage every 250 ms and may cause fluctuation in the reading, use lower value or base line)

5.4.6 Efficiency Test (700-mA Load)

- Verify that input current to TX is less than 350 mA with input voltage at 19 V_{DC}
- Turn *OFF* Transmitter Power Supply (19)

5.4.7 Adapter Test (700-mA Load)

- Connect 6-V, ± 200 mV power supply with current limit set to 1.0 A to J1 and return to J2 on the HPA764-005 receiver.
- Adjust load current to 700 mA, ± 50 mA
- Turn on power supply
- Verify that:
 1. UUT: TP7 V_{OUT} is 6.5 V to 7.1 V
 2. Transmitter: Status LED D5 is off

6 Test Results

6.1 Load Step

The procedure for load step is as follows:

- Set up the test bench as described in [Section 5](#).
- Power TX with 19 V.
- Provide a load step from no load (high impedance) to 11.5 Ω or 600 mA (if using current source load).
- Monitor load current, rectifier voltage, and output voltage as shown in [Figure 3](#).

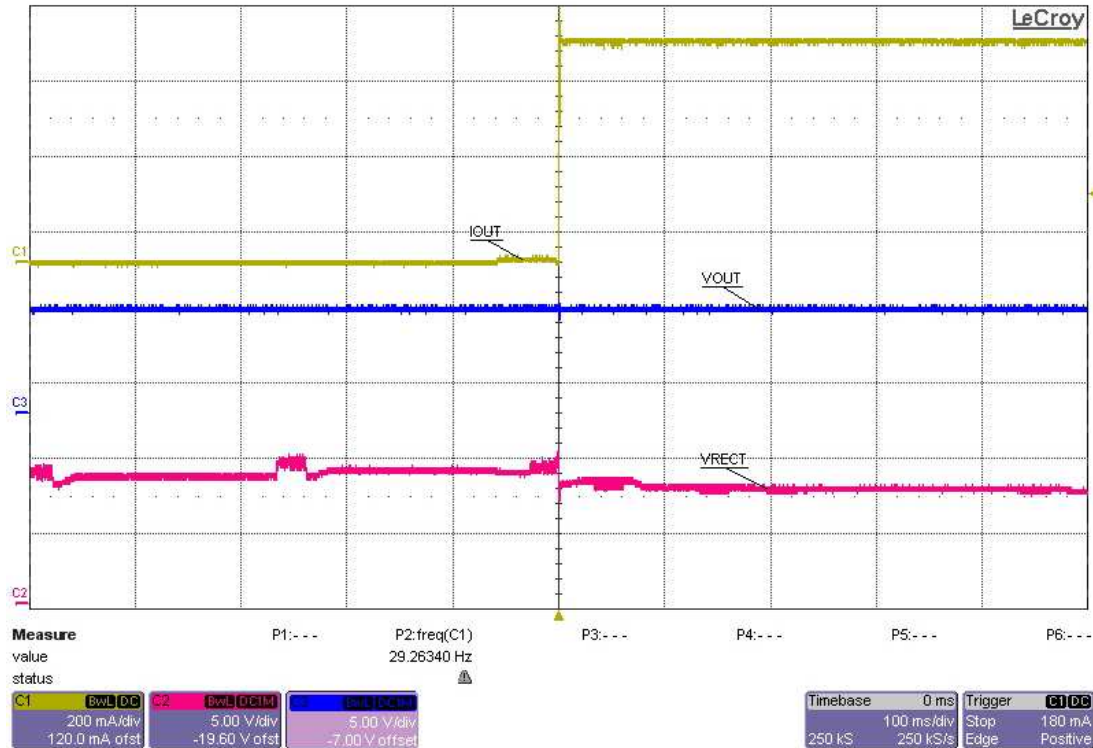


Figure 3. Load Step, 0 mA to 600 mA

6.2 Load Dump

The procedure for load dump is as follows:

- Set up the test bench as described in [Section 5](#).
- Power TX with 19 V
- Provide a load dump from 14 Ω or 500 mA (if using a current source load) to no load (high impedance).
- Monitor load current, rectifier voltage, and output voltage as shown in [Figure 4](#).

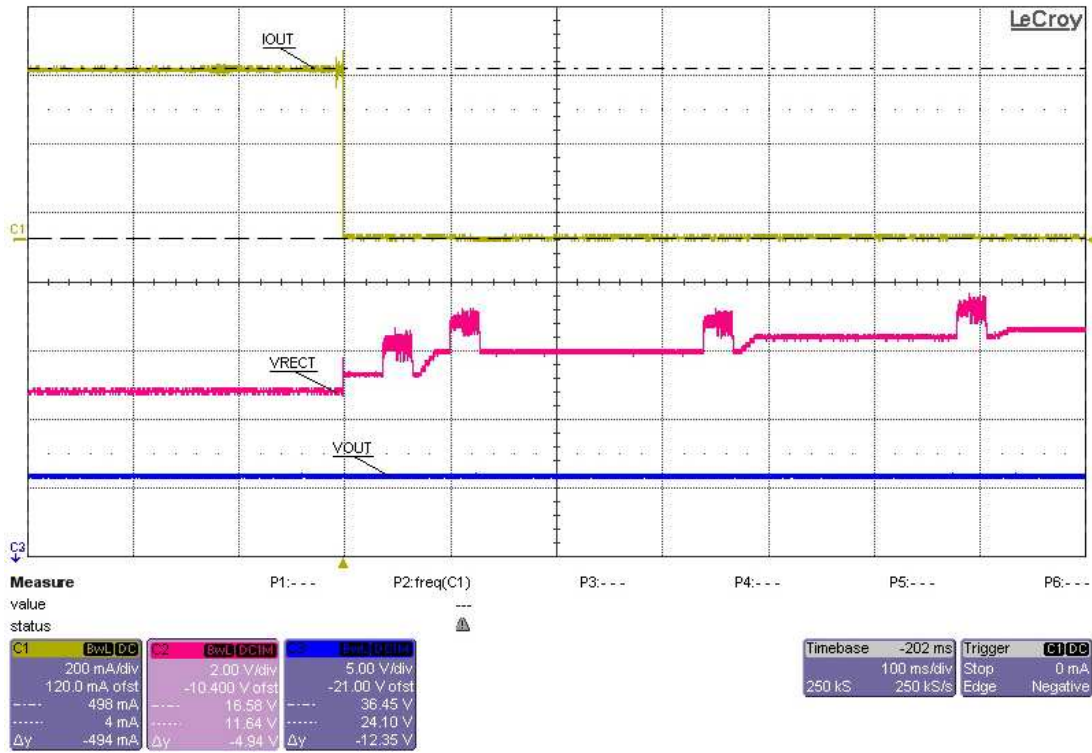


Figure 4. Load Dump, 500 mA to 0 mA

6.3 Start-Up

These procedures demonstrates start-up:

- Set up the test bench as described in [Section 5](#).
- Power TX with 19 V
- Trigger scope sweep on TP2 AC IN

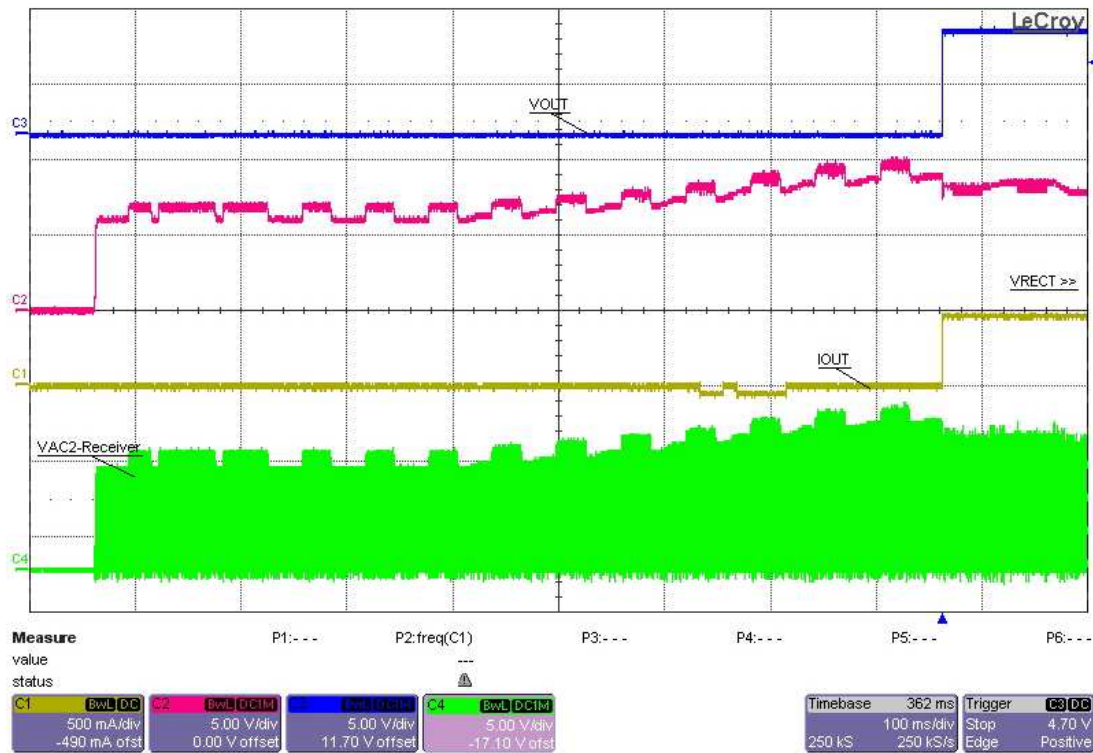


Figure 5. Start-Up

6.4 Efficiency

Figure 6 shows the efficiency data for the wireless power receiver, bq51010B. The efficiency data are measured from 100- to 700-mA load.

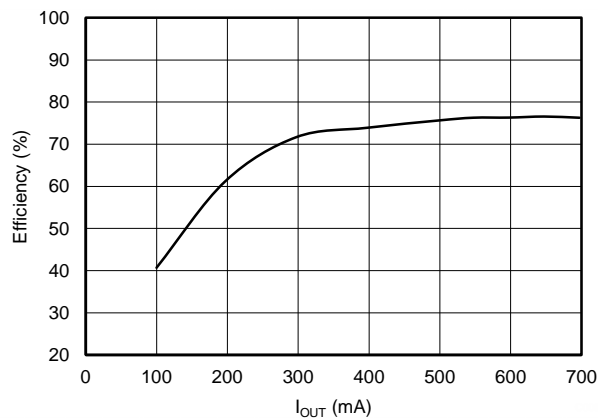


Figure 6. Efficiency for the bq51010B versus I_{OUT}

6.5 Thermal Performance

This section shows a thermal image of the bq51010BEVM-764. A 7.0-V output is used at a 720-mA load. There is no air flow and the ambient temperature is 25°C. The peak temperature of the IC, 44.9°C, is well below the maximum recommended operating condition listed in the data sheet.

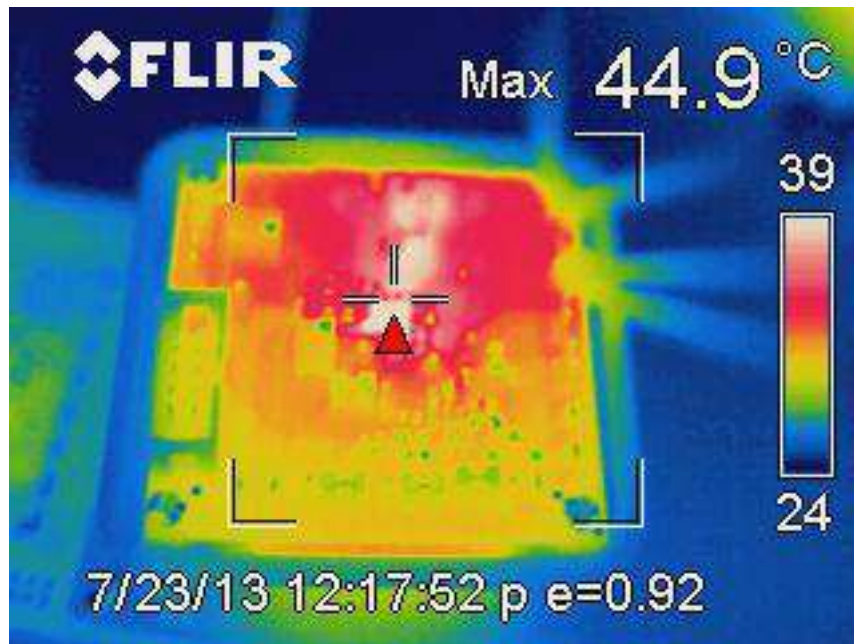


Figure 7. Thermal Image

7 Layout and Bill of Material

7.1 Layout

7.1.1 Printed-Circuit Board Layout Guideline

The primary concerns when laying out a custom receiver PCB are:

- AC1 and AC2 trace resistance
- OUT trace resistance
- RECT trace resistance
- GND connection
- Copper weight ≥ 2 oz

For a 720-mA load current application, the current rating for each net is as follows:

- AC1 = AC2 = 900 mA
- BOOT1 = BOOT2 = 10 mA
- RECT = 750 mA
- OUT = 750 mA
- COM1 = COM2 = 300 mA
- CLAMP1 = CLAMP2 = 500 mA
- ILIM = 10 mA
- AD = AD_EN = TS-CTRL = EN1 = EN2 = TERM = FOD = 1 mA
- CHG = 10 mA

It is also recommended to have the following capacitance on RECT and OUT:

- RECT $\geq \pm 10 \mu\text{F}$
- OUT $\geq 1 \mu\text{F}$

It is always a good practice to place high-frequency bypass capacitors of 0.1 μF next to RECT and OUT.

Figure 8 illustrates an example of a WCSP layout:

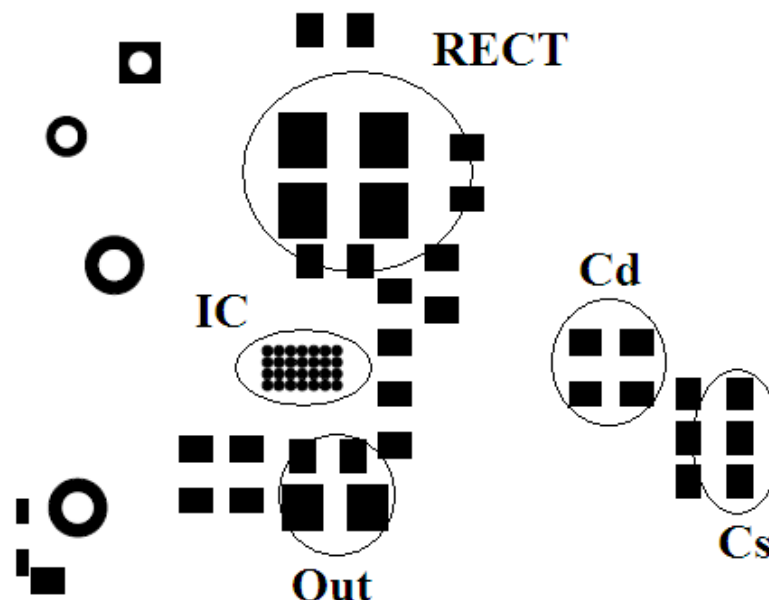


Figure 8. bq51010BEVM-764 Layout Example

7.1.2 Layout

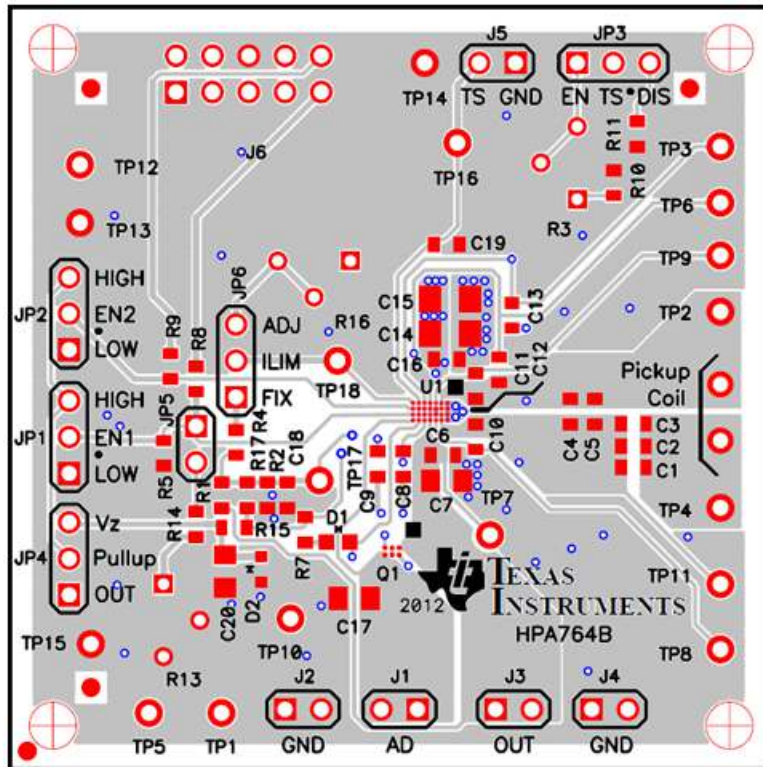


Figure 9. bq51010BEVM-764 Top Assembly

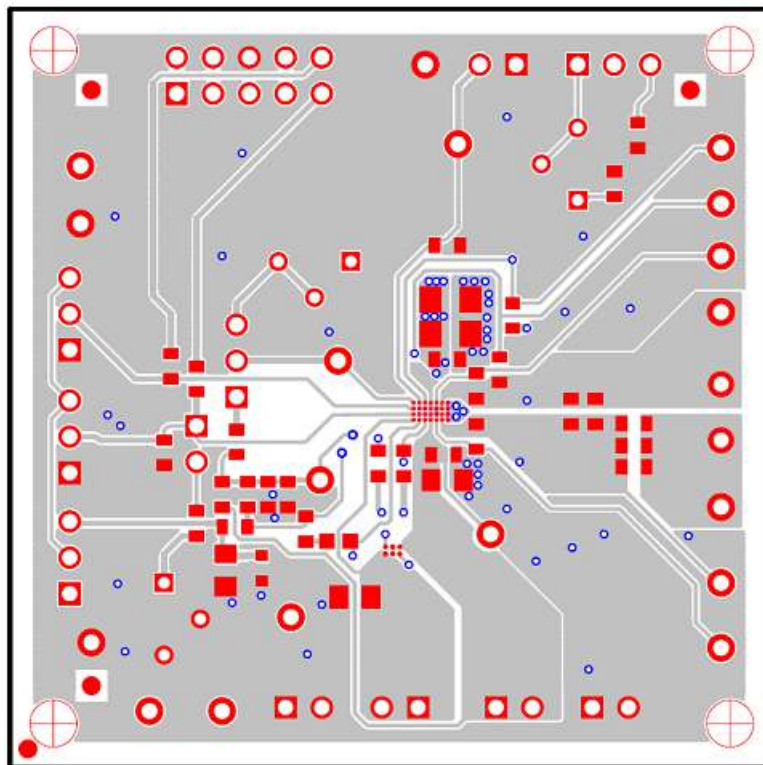


Figure 10. bq51010BEVM-764 Top Layer

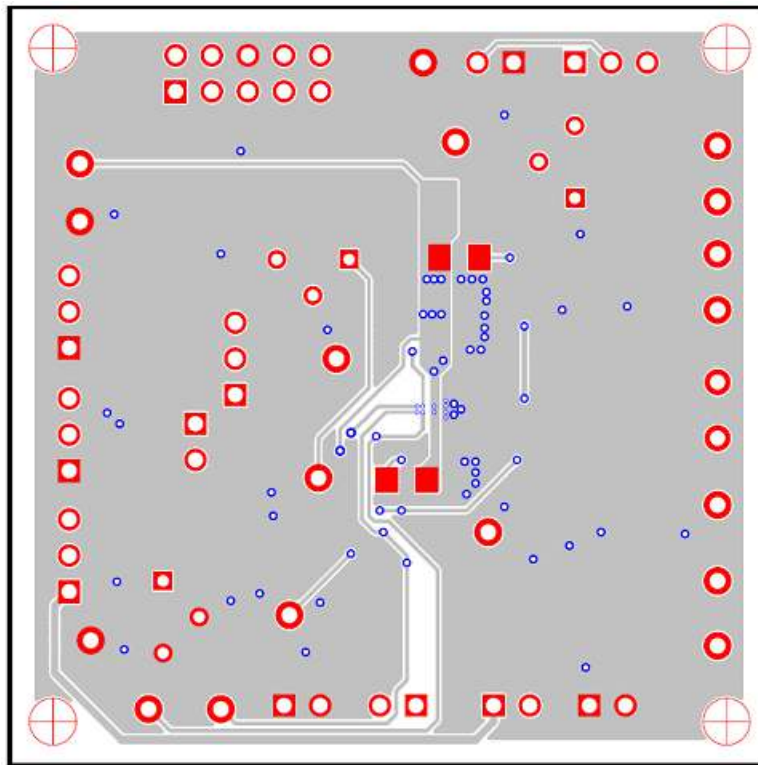


Figure 11. bq51010BEVM-764 Bottom Copper Layer

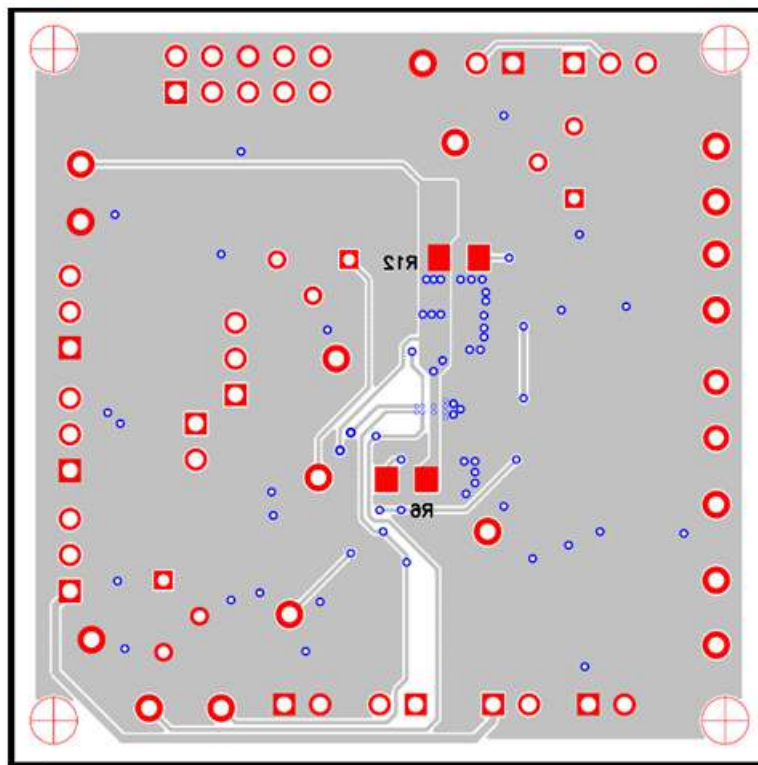


Figure 12. bq51010BEVM-764 Bottom Assembly

7.2 Bill of Materials (BOM)

Table 3. bq51010BEVM-764 Bill of Materials

COUNT					RefDes	Value	Description	Size	Part Number	MFR
001	002	003	004	005	RefDes	Value	Description	Size	Part Number	MFR
1	1	1	1	1	C1	68nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	1	1	1	0	C2	68nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
0	0	0	0	1	C2	12nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	1	1	1	1	C3	47nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	1	1	1	0	C4	1800pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
0	0	0	0	1	C4	1500pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	1	1	1	1	C5	100pF	Capacitor, Ceramic, 50V, C0G, 5%	0603	Std	Std
4	4	4	4	4	C6, C16, C18, C19	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
3	3	3	3	3	C7, C17, C20	1.0uF	Capacitor, Ceramic, 50V, X5R, 10%	0805	Std	Std
2	2	2	2	2	C8, C13	22nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
2	2	2	2	2	C9, C12	0.47uF	Capacitor, Ceramic, 25V, X5R, 10%	0603	Std	Std
2	2	2	2	2	C10, C11	0.01uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
2	2	2	2	2	C14, C15	10uF	Capacitor, Ceramic, 25V, X5R, 10%	1206	Std	Std
1	1	1	1	1	D1	LTST-C190GKT	Diode, LED, Green, 2.1-V, 20-mA, 6-mcd	0603	LTST-C190GKT	Lite On
1	1	1	1	1	D2	5.1V	Diode, Zener, 5.1V, 300mW	SOD-523	BZT52C5V1T-7	Diodes, Inc.
5	5	5	5	5	J1, J2, J3, J4, J5	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
1	1	1	1	1	J6	N2510-6002-RB	Connector, Male Straight 2x5 pin, 100mil spacing, 4 Wall	0.338 x 0.788 inch	N2510-6002-RB	3M
4	4	4	4	4	JP2, JP3, JP4, JP6	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
1	0	1	0	1	JP1	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
0	1	0	1	0	JP5	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
1	0	1	0	1	Q1	CSD75205W1015	MOSFET, Dual PChan, -20V, 1.2A, 190 milliOhm	CSP 1x1.5mm	CSD75205W1015	TI
0	0	0	0	0	R1	Open	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	0	0	0	0	R2	150	Resistor, Chip, 1/16W, 1%	0603	Std	Std
0	0	1	0	0	R2	196	Resistor, Chip, 1/16W, 1%	0603	Std	Std
0	1	0	1	1	R2	200	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	1	1	1	1	R3	200k	Potentiometer, 1/4 in. Cermet, 12-Turn, Top-Adjust	0.25x0.17	3266W-1-204LF	Bourns
0	0	1	0	0	R4	75	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	1	0	1	1	R4	110	Resistor, Chip, 1/16W, 1%	0603	Std	Std
0	0	0	0	0	R5	Open	Resistor, Chip, 1/16W, 1%	0603	Std	Std
0	0	0	0	0	R6, R12	Open	Resistor, Metal Film, 1/4 watt, ± 1%	1206	CRCW120624R0FKEA	Vishay
1	1	1	1	1	R7	1.50K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	1	1	1	1	R8, R9	200	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	1	1	1	1	R10	499	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	1	1	1	1	R11	10.0k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
0	1	0	1	0	R14	1.0k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	1	1	1	1	R15	1.0K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
0	1	0	1	0	R13	20k	Potentiometer, 1/4 in. Cermet, 12-Turn, Top-Adjust	0.25x0.17	3266W-1-203LF	Bourns

Table 3. bq51010BEVM-764 Bill of Materials (continued)

COUNT					RefDes	Value	Description	Size	Part Number	MFR
001	002	003	004	005	RefDes	Value	Description	Size	Part Number	MFR
1	1	1	1	1	R16	5k	Potentiometer, 1/4 in. Cermet, 12-Turn, Top-Adjust	0.25x0.17	3266W-1-502LF	Bourns
0	0	1	0	0	R17	20K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
0	1	0	1	0	R17	42.2K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
0	0	0	0	1	R17	36K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
15	15	15	15	15	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP16, TP17, TP18	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
3	3	3	3	3	TP13, TP14, TP15	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	0	0	0	0	U1	bq51013AYFP	IC, Wireless Secondary-Side Power Controller	DSBGA	bq51013AYFP	TI
0	1	0	0	0	U1	bq51050BYFP	IC, Wireless Secondary-Side Power Controller and Battery Charger	DSBGA	bq51050BYFP	TI
0	0	1	0	0	U1	bq51013BYFP	IC, Wireless Secondary-Side Power Controller	DSBGA	bq51013BYFP	TI
0	0	0	1	0	U1	bq51051BYFP	IC, Wireless Secondary-Side Power Controller and Battery Charger	DSBGA	bq51013BYFP	TI
0	0	0	0	1	U1	bq51010BYFP	IC, Wireless Secondary-Side Power Controller	DSBGA	bq51013BYFP	TI
5	5	5	5	5	--		Shunt, 100-mil, Black — See note 6		929950-00	3M
1	1	1	1	1	--		PCB, 2.1" x 2.1" x 0.031"		HPA764	Any
1	1	1	1	1	--		Case Modified Polycase LP-11B with 4 screws — See note 7		J-6838A	Polycase
1	1	1	1	0	--		Coil, RX with Attractor		IWAS-4832FF-50 WR-483250-15M2-G 760308103204	Vishay TDK Wyrth
0	0	0	0	1			Coil, RX with Attractor — See note 8		IWAS4832ECEB160J50	Vishay
1	1	1	1	1			Tape segment, Low Static Polyimide Film — See note 9	1.5" x 2.3"	5419-1 1/2"	3M
1	1	1	1	1	Label	Label	Thermal Label — See note 10		THT-53-423-3	Brady
Notes:										
1. These assemblies are ESD sensitive, observe ESD precautions.										
2. These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.										
3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.										
4. Ref designators marked with an asterisk ("**") cannot be substituted. All other components can be substituted with equivalent MFG's components.										
5. Tape "Coil, RX" into bottom of case, centered, coil side down, lead wires passing through milled groove.										
6. Install Shunts on:										
		JP1: (Only for HPA764-001, 003, & 005) between EN1/TERM and LOW				JP4: between Pull-up and Vz				
		JP2: between EN2 and LOW				JP5: (Only for HPA764-002 and HPA764-004) between two ends				
		JP3: between TS and DIS								
7. Install PCB in case using screws provided with case										
8. WR483225-16M6-TI3 from TDK coil can also be used as second option.										
9. Used to secure RX coil to case. Cut tape section from 36 yard roll identified in part number field.										
10. Install label on back of PCB near J6 on the top edge of the PCB after final wash (box). Text shall be 8 pt font or lower. Text shall be per Table 1 . The ref designators should not be hidden by the label.										
		Table 1								
		Assembly Number		Text						
		HPA764-001		bq51013AEVM-764						
		HPA764-002		bq51050BEVM-764						
		HPA764-003		bq51013BEVM-764						

Table 3. bq51010BEVM-764 Bill of Materials (continued)

COUNT					RefDes	Value	Description	Size	Part Number	MFR
001	002	003	004	005						
			HPA764-004		bq51051BEVM-764					
			HPA764-005		bq51010BEVM-764					

Revision History

Changes from Original (August 2013) to A Revision	Page
• Added Wyrth part 760308103204, in 'Coil, RX with Attractor' row of BOM.	17

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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As noted in the EVM User's Guide and/or EVM itself, this EVM and/or accompanying hardware may or may not be subject to the Federal Communications Commission (FCC) and Industry Canada (IC) rules.

For EVMs **not** subject to the above rules, this evaluation board/kit/module is intended for use for ENGINEERING DEVELOPMENT, DEMONSTRATION OR EVALUATION PURPOSES ONLY and is not considered by TI to be a finished end product fit for general consumer use. It generates, uses, and can radiate radio frequency energy and has not been tested for compliance with the limits of computing devices pursuant to part 15 of FCC or ICES-003 rules, which are designed to provide reasonable protection against radio frequency interference. Operation of the equipment may cause interference with radio communications, in which case the user at his own expense will be required to take whatever measures may be required to correct this interference.

General Statement for EVMs including a radio

User Power/Frequency Use Obligations: This radio is intended for development/professional use only in legally allocated frequency and power limits. Any use of radio frequencies and/or power availability of this EVM and its development application(s) must comply with local laws governing radio spectrum allocation and power limits for this evaluation module. It is the user's sole responsibility to only operate this radio in legally acceptable frequency space and within legally mandated power limitations. Any exceptions to this are strictly prohibited and unauthorized by Texas Instruments unless user has obtained appropriate experimental/development licenses from local regulatory authorities, which is responsibility of user including its acceptable authorization.

For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant

Caution

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

For EVMs annotated as IC – INDUSTRY CANADA Compliant

This Class A or B digital apparatus complies with Canadian ICES-003.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Concerning EVMs including radio transmitters

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concerning EVMs including detachable antennas

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Cet appareil numérique de la classe A ou B est conforme à la norme NMB-003 du Canada.

Les changements ou les modifications pas expressément approuvés par la partie responsable de la conformité ont pu vider l'autorité de l'utilisateur pour actionner l'équipement.

Concernant les EVMs avec appareils radio

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

【Important Notice for Users of EVMs for RF Products in Japan】

This development kit is NOT certified as Confirming to Technical Regulations of Radio Law of Japan

If you use this product in Japan, you are required by Radio Law of Japan to follow the instructions below with respect to this product:

1. Use this product in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use this product only after you obtained the license of Test Radio Station as provided in Radio Law of Japan with respect to this product, or
3. Use of this product only after you obtained the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to this product. Also, please do not transfer this product, unless you give the same notice above to the transferee. Please note that if you could not follow the instructions above, you will be subject to penalties of Radio Law of Japan.

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Your Sole Responsibility and Risk. You acknowledge, represent and agree that:

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3. Since the EVM is not a completed product, it may not meet all applicable regulatory and safety compliance standards (such as UL, CSA, VDE, CE, RoHS and WEEE) which may normally be associated with similar items. You assume full responsibility to determine and/or assure compliance with any such standards and related certifications as may be applicable. You will employ reasonable safeguards to ensure that your use of the EVM will not result in any property damage, injury or death, even if the EVM should fail to perform as described or expected.
4. You will take care of proper disposal and recycling of the EVM's electronic components and packing materials.

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